

RELIABILITY TEST RESULT

Product name : S-24C04DI-A8TxU5

Package type : DFN-8(2030)

No.	Test item	Test Condition	Test Time	r/n	Criterion
1	High-temperature operation	Ta=125 °C, V=Vopr max.	1000 h	0/22	Satisfies the product standard
2	Temperature humidity bias #1	Ta=85 °C, RH=85 %, V=Vopr max.	1000 h	0/22	Satisfies the product standard
3	Pressure cooker bias #1	Ta=125 °C, RH=85 %, P=2×10 ⁵ Pa V = Vopr max.	100 h	0/22	Satisfies the product standard
4	Storage in high temperature	Ta=150 °C	1000 h	0/22	Satisfies the product standard
5	Storage in low temperature	Ta=-65 °C	1000 h	0/22	Satisfies the product standard
6	Write/Erase Cycle	Ta=25 °C, V=Vopr max.	1×10 ⁶ cycles	0/22	Satisfies the product standard
7	Temperature Cycle (Gas phase) #1	Ta=150 °C ⇔ -65 °C 15 minutes for each	500 cycles	0/22	Satisfies the product standard
8	Resistance to soldering heat (reflow soldering) #2	T=260 °C ,10 s	3 times	0/22	Satisfies the product standard No abnormality by appearances
9	Solderability #3	T=245 °C Solder material : Sn-3.0Ag-0.5Cu	5 s	0/11	Solder should be applied at 95% or more of solderability judgment area.
10	Whisker - 1 (Temperature / Humidity Storage)	Ta=30 °C, RH=60%	4000 h	0/6	Whisker should be less than 40μm
11	Whisker - 2 (Temperature Cycling)	Ta=85 °C ⇔ -40 °C	1500 cycles	0/6	Whisker should be less than 45μm
12	Whisker - 3 (High Temperature / Humidity Storage)	Ta=55 °C, RH=85 %	4000 h	0/6	Whisker should be less than 40μm
13	Solder Joint Reliability (shear test) #3	Ta=125 °C ⇔ -40 °C Solder material : Sn-3.0Ag-0.5Cu	2000 cycles	0/22	After temperature cycle test, keep strength for shear stress more than the 50 % of initial mean value.
14	ESD - 1 (Human Body Model)	V=±2000 V, C=100 pF, R=1.5 kΩ Ground : V _{CC} / GND	5 pulses	0/5	Satisfies the product standard
15	ESD - 2 (Charged Device Model)	V=±500V charged, discharged	1 pulse	0/5	Satisfies the product standard
16	Latch up (Pulsed current injection test)	±100 mA, V =Vopr max.	1 pulse	0/5	No latch up

Remark : Vopr max. =Maximum operation voltage

#1,2,3 : Each test designated # is performed after Pre-Treatment finished.

Pre-Treatment consists of High Temperature Storage ,Temperature Humidity Storage and Soldering Heat. (See the table below.)

Pre Treatment (#1)		
High Temp. Storage	Temperature Humidity Storage	Soldering Heat
Ta=125 °C t=24 h	Ta=85 °C RH=85 % t=168 h	Reflow 3 times T=260 °C t=10 s

Pre Treatment (#2)		
High Temp. Storage	Temperature Humidity Storage	Soldering Heat
Ta=125 °C t=24 h	Ta=85 °C RH=85 % t=168 h	—

Pre Treatment (#3)		
High Temp. Storage	Temperature Humidity Storage	Soldering Heat
—	Ta=105 °C RH=100 % t=8 h	—